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(54) **POWER CONVERSION DEVICE**

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(57) **ABSTRACT**

The power converter **A1** includes a semiconductor device **B1**, and a substrate H on which the semiconductor device **B1** is mounted, where the semiconductor device **B1** includes a control chip constituting a primary control circuit, a semiconductor chip constituting a secondary power circuit, and a transmission circuit for electrically insulating the primary control circuit and the secondary power circuit and for signal transmission between the primary control circuit and the secondary power circuit. The substrate H has a conductive portion K. The power converter **A1** includes a connecting terminal **T1** disposed on the substrate H and electrically connected to the conductive portion K. The power converter **A1** includes a conductive path **D1** that is at least partially formed by the conductive portion K of the substrate H, and that electrically connects the primary control circuit and the connecting terminal **T1**. Such a configuration contributes to downsizing the power converter **A1**.